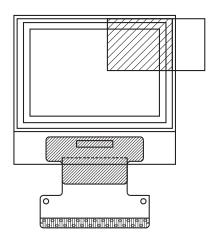


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COMPLIANT

96 x 64 Graphic OLED



MECHANICAL DATA				
ITEM	STANDARD VALUE	UNIT		
Module dimension	24.9 x 22.95 x 1.65			
Viewing area	21.953 x 15.424			
Active area	19.946 x 13.418	mm		
Dot size	0.186 x 0.188	mm		
Dot pitch	0.208 x 0.210			
Mounting hole	n/a			

FEATURES

Type: graphic

Display format: 96 x 64 dotsBuilt-in controller: SSD1305Z

Duty cycle: 1/64+3 V power supply

• Interface: 6800, 8080, SPI, I2C

With polarizer

Material categorization: for definitions of compliance

please see www.vishay.com/doc?99912

ABSOLUTE MAXIMUM RATINGS					
ITEM	CVMPOL	STANDAF	STANDARD VALUE		
ITEM	SYMBOL	MIN.	MAX.	UNIT	
Supply voltage for logic (1)(2)	V _{DD}	-0.3	4	V	
Supply voltage for display (1)(2)	V _{CC}	0	15]	
Operating temperature	T _{OP}	-40	+80	°C	
Storage temperature	T _{STG}	-40	+80		

Notes

- $^{(1)}$ All the above voltages are on the basis of "V_{SS} = 0 V"
- When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

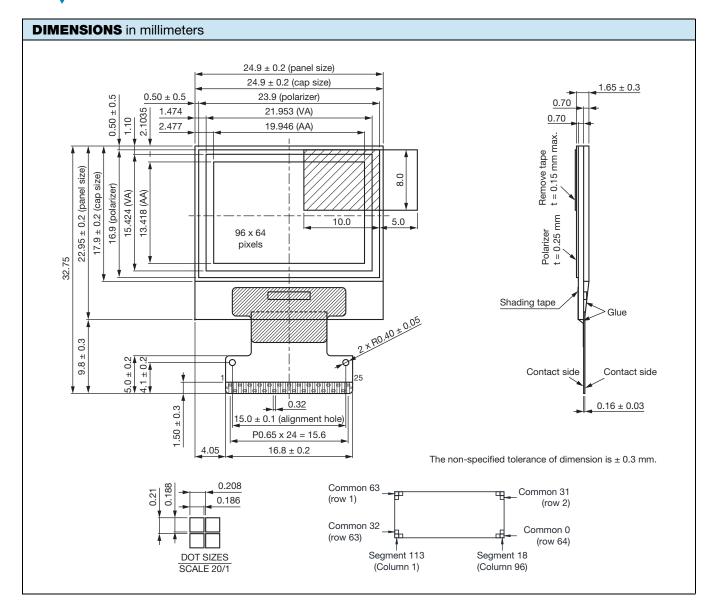
ELECTRICAL CHARACTERISTICS							
ITEM	CYMPOL	OVER DOUBLE ON THE OWNER OF THE OWNER OWNER OF THE OWNER OWNER OF THE OWNER OWNE	ST	STANDARD VALUE			
HEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	
Supply voltage for logic	V_{DD}	=	2.8	3.0	3.3		
Supply voltage for display	V _{CC}	=	11	12	13		
Input high voltage	V _{IH}	-	0.8 V _{DD}	-	V _{DDI/O}		
Input low voltage	V _{IL}	=	0	-	0.2 V _{DD}]	
Output high voltage	V _{OH}	=	0.9 V _{DD}	-	V _{DDI/O}		
Output low voltage	V _{OL}	=	0	-	0.1 V _{DD}		
50 % check board operating current	I _{CC}	V _{CC} = 12 V	5.8	6.0	7.5	mA	

OPTIONS				
		EMITTING COLOR		
YELLOW	GREEN	RED	BLUE	WHITE
Yes	=	=	-	=

Revision: 11-Aug-17 **1** Document Number: 37835 For technical questions, contact: displays@vishay.com



INTER	FACE PIN	FUN	ICTION				
PIN NO.	SYMBOL	I/O			FUNCTION		
1	NC (GND)	-	The supporting pins	Reserved pin (supporting pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground			
2	V _{CC}	Р	Power supply for OLED panel This is the most positive voltage supply pin of the chip. It must be supplied externally				
3	V_{SS}	Р	Ground of logic circ This is a ground pin		rence for the logic pir	ns. It must be connect	ed to external ground
4	V _{DD}	Р	Power supply for log This is a voltage sup	gic circuit oply pin. It must be co	onnected to external s	source	
5	V _{DDI/O}	Р	Power supply for in always be equal or l		should be match wi	th MCU interface volt	age level. V _{DDI/O} must
6	DC1		Communicating pro	tocol select. These pi	ns are MCU interface	selection input. See t	he following table:
6	BS1			68XX-parallel	80XX-parallel	Serial	I ² C
		I	BS1	0	1	0	1
7	BS2		BS2	1	1	0	0
8	CS#	I	Chip select This pin is the chip s	select input. The chip	is enabled for MCU of	communication only w	hen CS# is pulled low
9	RES#	I		This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low Power reset for controller and driver This pin is reset signal input. When the pin is low, initialization of the chip is executed			
10	D/C#	-	data. When the pin is relationship to MCU When the pin is pulle	nmand control pin. Wi s pulled low, the input interface signals, ple ed high and serial inte data at SDIN will be t	at D7 to D0 will be tra ase refer to the timin erface mode is selected	ansferred to the comm g characteristics diagr ed, the data at SDIN is	D0 is treated as display and register. For detail ams. treated as data. When mode, this pin acts as
11	R/W#	1	read / write (R / W#) When 80XX interface	erface input. When intended selection input. Pull t	his pin to "high" for re is pin will be the write	ead mode and pull it to	this pin will be used as o "low" for write mode. te operation is initiated
12	E / RD#	I	This pin is MCU into the enable (E) signal When connecting to	Read / write enable or read This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the enable (E) signal. Read / write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low			
13							
14							
15			Host data in put / or	utput bus			
16	D0 +- D7	1/0					data bus. When serial
17	D0 to D7	I/O	,		•		input SCLK. When I ² C in application and D0
18			is the serial clock in		roa togothor and core	TO GO OD TOUL GITG OD TH	m application and Bo
19							
20							
21	I _{REF}	I				connected between th	nis pin and V _{SS} . Set the
22	V _{COMH}	0	0 1 0		tput high level for CC	M signals. A capacito	r should be connected
23	V _{CC}	Р	Power supply for OI This is the most pos		in of the chip. It mus	t be supplied externall	у
24	V _{LSS}	Р	Ground of analog ci	rcuit. This is an analo	g ground pin. It shou	ld be connected to $V_{\rm SS}$	s externally
25	NC (GND)	1	Reserved pin (supporting pinsonnected to extern	s can reduce the infl	uences from stresses	s on the function pins	s. These pins must be





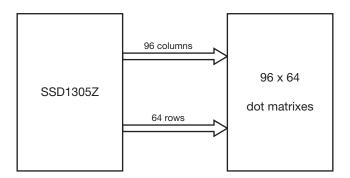
MODULE CLA	SSIFICATION INFORMA	ATION
OLED -	096 O 064 A	- L P P 3 N 0 0 000
1	2 3 4 5	6 7 8 9 10 11 12 13
1	Brand	Vishay Intertechnology, Inc.
2	Horizontal format	96 columns
		F: COG type, with frame
	Display type	H: graphic type
3		N: character type
		O: COG type
		Y: tab type
4	Vertical format	64 lines
5	Serials code	A
		A: amber
		B: blue
		C: full color
		G: green
6	Emitting color	L: yellow R: red
		S: sky blue
		W: white
		X: yellow / sky blue (dual color)
		Y: yellow green
		N: without polarizer
7	Polarizer	P: with polarizer
	5	A: active matrix
8	Display mode	P: passive matrix
0	Driver veltere	3: 3.0 V to 3.3 V
9	Driver voltage	5: 5.0 V
10	Touch panel	N: without touch panel
10	rodon paner	T: with touch panel
		0: standard
		1: sunlight readable
11	Products type	2: transparent OLED (TOLED)
		3: flexible OLED
		4: OLED for lighting
		0: standard (A level)
10	Droduot grades	2: B level
12	Product grades	3: C level 4: high class (AA level)
		4: nigh class (AA level) 5: customer offerings
13	Serial number	Application serial number (000 to ZZZ)
	Condition 1001	Application solid Hambor (666 to 222)



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GENERAL SPECIFICATIONS				
ITEM	DIMENSION	UNIT		
Number of characters	96 x 64 dots			
Module dimension	24.9 x 22.95 x 1.65	mm		
View area	21.953 x 15.424	mm		
Active area	19.946 x 13.418	mm		
Dot size	0.186 x 0.188	mm		
Dot pitch	0.208 x 0.210	mm		
Panel type	OLED, yellow			
Duty	1/64			
IC	SDD1305Z			

FUNCTION BLOCK DIAGRAM



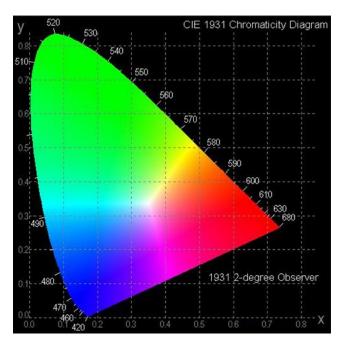
Notes

- V_{CC} supplied externally
- For more information, please refer to Application Note provided by Vishay



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OPTICAL CHARACTERISTICS						
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
View angle	(V)θ		160	-	-	deg
view arigie	(H)φ		160	-	-	ueg
Contrast ratio	CR	Dark	2000 : 1	-	-	-
Response time	t _{rise}		-	10	-	μs
nesponse time	t _{fall}		-	10	-	μs
Display with 50 % check board brightness			80	100	-	cd/m ²
CIE _x (yellow)	(CIE1931)		0.45	0.47	0.49	
CIE _y (yellow)	(CIE1931)		0.48	0.50	0.52	



OLED LIFETIME			
ITEM	CONDITIONS	MIN.	TYP.
Operating life time	T _A = 25 °C, initial 50 % check board brightness typical value	50 000 h	-

Notes

- Life time is defined the amount of time when the luminance has decayed to < 50 % of the initial value
- This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (PDF) for the product under normal use conditions
- Screen saving mode will extend OLED lifetime

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RELABILITY		
ENVIRONMENTAL TEST		
TEST ITEM	CONTENT OF TEST	TEST CONDITION
High temperature storage	Endurance test applying the high storage temperature for a long time	80 °C, 240 h
Low temperature storage	Endurance test applying the low storage temperature for a long time	-40 °C, 240 h
High temperature operation	Endurance test applying the electric stress (voltage and current) and the thermal stress to the element for a long time	80 °C, 240 h
Low temperature operation	Endurance test applying the electric stress under low temperature for a long time	-40 °C, 240 h
High temperature / humidity storage	Endurance test applying the high temperature and high humidity storage for a long time	60 °C, 90 % RH, 240 h
Temperature cycle	Endurance test applying the low and high temperature cycle -40 °C 25 °C 80 °C 30 min 5 min 30 min 1 cycle	-40 °C / 80 °C, 100 cycles
MECHANICAL TEST	,	
Vibration test	Endurance test applying the vibration during transportation and using	10 Hz to 22 Hz for 1.5 mm peak-to-peak, 22 Hz to 500 Hz for 1.5 <i>g</i> , total 0.5 h
Shock test	Constructional and mechanical endurance test applying the shock during transportation	50 <i>g</i> half sin wave 11 ms, 3 times of each direction
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air	115 mbar, 40 h
OTHERS		
Static electricity test	Endurance test applying the electric stress to the terminal	$V_S = \pm~600~V$ (contact), $\pm~800~V$ (air), $R_S = 330~\Omega$, $C_S = 150~pF$, 10 times

Note

Supply voltage for OLED system = operating voltage at 25 °C

TEST AND MEASUREMENT CONDITIONS

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hours prior to conducting the failure test at $23 \,^{\circ}\text{C} \pm 5 \,^{\circ}\text{C}$, $55 \,^{\circ}\text{M} \pm 15 \,^{\circ}\text{RH}$
- 2. All-pixels-on is used as operation test pattern
- 3. The degradation of polarizer are ignored for high temperature storage, high temperature / humidity storage, temperature cycle

EVALUATION CRITERIA

- 4. The function test is OK
- 5. No observable defects
- 6. Luminance: > 50 % of initial value
- 7. Current consumption: within \pm 50 % of initial value

APPENDIX: RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



INSI	PECTION SPECIF	FICATION				
NO.	ITEM		CRITERIO	N		AQL
01	Electrical testing Black or white	1.1 Missing vertical, horizonta 1.2 Missing character, dot or 1.3 Display malfunction 1.4 No function or no display 1.5 Current consumption exc 1.6 OLED viewing angle defect 1.7 Mixed product types 1.8 Contrast defect 2.1 White and black spots on	icon eeds product specific ct	cations	nite or black spots present	0.65
02	spots on OLED (display only)	·	2.2 Densely spaced: no more than two spots or lines within 3 mm			2.5
03	OLED black spots, white spots,	3.1 Round type: as following $\Phi = (x + y) / 2$ $\Rightarrow x \mid x \mid y$	drawing	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	ACCEPTABLE QTY Accept no dense 2 1 0	2.5
	contamination (non-display)	3.2 Line type (as following drawing)	LENGTH - L ≤ 3.0 L ≤ 2.5 -	$\begin{tabular}{c} \textbf{WIDTH} \\ W \le 0.02 \\ 0.02 < W \le 0.03 \\ 0.03 < W \le 0.05 \\ 0.05 < W \\ \end{tabular}$	ACCEPTABLE QTY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge specifications, not easy to fin specify direction.		SIZE Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total QTY	ACCEPTABLE QTY Accept no dense 3 2 0 3	2.5
05	Scratches	Follow no. 3 OLED black spots,	white spots, contami	nation		
06	Chipped glass	Symbols: x: chip length k: seal width l: electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and z: chip thickness z ≤ 1/2 t 1/2 t < z ≤ 2 t Note	y: chip width t: glass thickness d crack between pane y y: chip width Not over viewing a Not exceed 1/3 k	x y z	z: chip thickness a: OLED side length	2.5



NO	PECTION SPEC	JIFICATION	ODITEDION		1 40
NO.	ITEM	6.1.2 Corner crack:	CRITERION		AC
06	Chipped glass	U.T.2 COME CLACK.	x y		2.
		z: chip thickness	y: chip width	x: chip length	1
		$z \le 1/2 t$	Not over viewing area	x. chip length x ≤ 1/8 a	1
		1/2 t < z ≤ 2 t	Not exceed 1/3 k	x ≤ 1/8 a	1
		Note	Not exceed 1/3 K	X ≤ 1/0 a	J
			os, x is total length of each chip		
		Symbols:			
		x: chip length	y: chip width	z: chip thickness	
		k: seal width	t: glass thickness	a: OLED side length	
		I: electrode pad length 6.2 Protrusion over term 6.2.1 Chip on electrode pa			
			×	z	
		y: chip width	x: chip length	z: chip thickness	1
		y ≤ 0.5 mm	x ≤ 1/8 a	0 < z ≤ t	
		6.2.2 Non-conductive port			J
06	Glass crack	y z			. 2.
		y: chip width	x: chip length	z: chip thickness	1
		y ≤ l	x ≤ 1/8 a	0 < z ≤ t	
		according to electrode te	sealed by the customer, the alignment		d]
			y ≤ 1/3	x ≤ a]



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INSPECTION SPECIFICATION					
NO.	ITEM	CRITERION	AQL		
08	Backlight elements	8.1 Illumination source flickers when lit	0.65		
		8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards	2.5		
		8.3 Backlight does not light or color wrong	0.65		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination	2.5		
		9.2 Bezel must comply with job specifications	0.65		
	PCB, COB	10.1 COB seal may not have pinholes larger than 0.2 mm or contamination	2.5		
		10.2 COB seal surface may not have pinholes through to the IC	2.5		
10		10.3 The height of the COB should not exceed the height indicated in the assembly diagram	0.65		
		10.4 There may not be more than 2 mm of sealant outside the seal area on the PCB. And there should be no more than three places	2.5		
		10.5 No oxidation or contamination PCB terminals	2.5		
		10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts	0.65		
		10.7 The jumper on the PCB should conform to the product characteristic chart	0.65		
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down	2.5		
	Soldering	11.1 No un-melted solder paste may be present on the PCB	2.5		
11		11.2 No cold solder joints, missing solder connections, oxidation or icicle	2.5		
11		11.3 No residue or solder balls on PCB	2.5		
		11.4 No short circuits in components on PCB	0.65		
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface pin (OLB) of TCP	2.5		
		12.2 No cracks on interface pin (OLB) of TCP	0.65		
12		12.3 No contamination, solder residue or solder balls on product	2.5		
		12.4 The IC on the TCP may not be damaged, circuits	2.5		
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever	2.5		
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color	2.5		
		12.7 Sealant on top of the ITO circuit has not hardened	2.5		
		12.8 Pin type must match type in specification sheet	0.65		
		12.9 OLED pin loose or missing pins	0.65		
		12.10 Product packaging must the same as specified on packaging specification sheet	0.65		
		12.11 Product dimension and structure must conform to product specification sheet	0.65		



CHECK ITEM	CLASSIFICATION	CRITERIA
No display	Major	
Missing line	Major	
Wissing line		
Pixel short	Major	
Darker short	Major	
Wrong display	Major	
Un-uniform	Major	
B/A x 100 % < 70 % A/C x 100 % < 70 %		A Normal B Dark pixel C Light pixel

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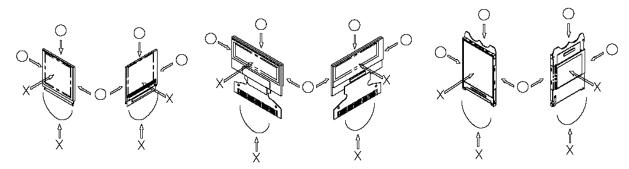
PRECAUTIONS IN USE OF OLED MODULES

MODULES

- 1. Avoid applying excessive shocks to module or making any alterations or modifications to it
- 2. Do not make extra holes on the printed circuit board, modify its shape or change the components of OLED display module
- 3. Do not disassemble the OLED display module
- 4. Do not operate it above the absolute maximum rating
- 5. Do not drop, bend or twist OLED display module
- 6. Soldering: only to the I/O terminals
- 7. Storage: please storage in anti-static electricity container and clean environment
- 8. It is pretty common to use "screen saver" to extend the lifetime and do not use fix information for long time in real application
- 9. Do not use fixed information in OLED panel for long time, that will extend "screen burn" effect time
- 10. Vishay has the right to change the passive components, including R2 and R3 adjust resistors. (Resistors, capacitors, and other passive components will have different appearance and color caused by the different supplier)
- 11. Vishay have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization, and the best product performance... etc, under the premise of not affecting the electrical characteristics and external dimensions, Vishay have the right to modify the version)

HANDLING PRECAUTIONS

- 1. Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position
- 2. If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance
- 3. If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections
- 4. The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module
- 5. When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape
- Scotch mending tape no. 810 or an equivalent
 Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since
 the surface of the polarizer will become cloudy. Also, pay attention that the following liquid and solvent may spoil the
 polarizer:
 - Water
 - Ketone
 - Aromatic solvents
- 6. Hold OLED display module very carefully when placing OLED display module into the system housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases



- 7. Do not apply stress to the LSI chips and the surrounding molded sections
- 8. Do not disassemble nor modify the OLED display module
- 9. Do not apply input signals while the logic power is off

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- 10. Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity
 - Be sure to make human body grounding when handling OLED display modules
 - · Be sure to ground tools to use or assembly such as soldering irons

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- . To suppress generation of static electricity, avoid carrying out assembly work under dry environments
- Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film
- 11. Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above no. 5
- 12. If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above

STORAGE PRECAUTIONS

- 1. When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps and, also, avoiding high temperature and high humidity environment or low temperature (less than 0 °C) environments. We recommend you to store these modules in the packaged state when they were shipped from Vishay. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them
- 2. If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above

DESIGNING PRECAUTIONS

- 1. The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen
- 2. To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible
- 3. We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD) (recommend value: 0.5 A)
- 4. Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices
- 5. As for EMI, take necessary measures on the equipment side basically
- 6. When fastening the OLED display module, fasten the external plastic housing section
- 7. If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module
 - Connection (contact) to any other potential than the above may lead to rupture of the IC

PRECAUTIONS WHEN DISPOSING OF THE OLED DISPLAY MODULES

1. Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations

OTHER PRECAUTIONS

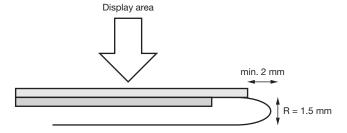
- 1. When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur. Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module
- 2. To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules
 - · Pins and electrodes
 - Pattern layouts such as the TCP and FPC
- 3. With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur
 - Design the product and installation method so that the OLED driver may be shielded from light in actual usage
 - · Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes

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- 4. Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design
- 5. We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise
- 6. Resistors, capacitors, and other passive components will have different appearance and color caused by the different supplier
- 7. Our company will has the right to upgrade and modify the product function
- 8. The limitation of FPC bending





Legal Disclaimer Notice

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